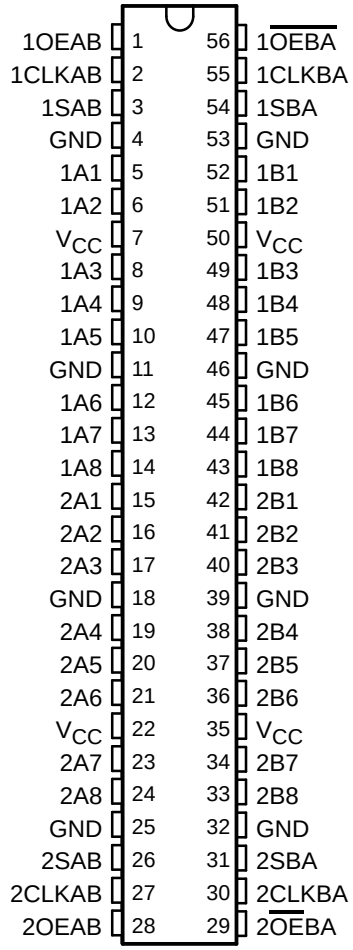
- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-II*B*™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Packaged in Plastic 300-mil Shrink Small-Outline Packages and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Spacings**

SN54ABT16651 . . . WD PACKAGE
SN74ABT16651 . . . DL PACKAGE
(TOP VIEW)



description

The ′ABT16651 is a 16-bit bus transceiver that consists of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. The device can be used as two 8-bit transceivers or one 16-bit transceiver.

Output-enable (OEAB and $\overline{\text{OEBA}}$) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A low input selects real-time data, and a high input selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the ′ABT16651.

Data on the A or B data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the select- or enable-control pins. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and $\overline{\text{OEBA}}$. In this configuration each output reinforces its input. Therefore, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remain at its last state.

PRODUCT PREVIEW

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description (continued)

To ensure the high-impedance state during power up or power down, $\overline{OEBA}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver (B to A). OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver (A to B).

The SN74ABT16651 is available in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54ABT16651 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16651 is characterized for operation from –40°C to 85°C.

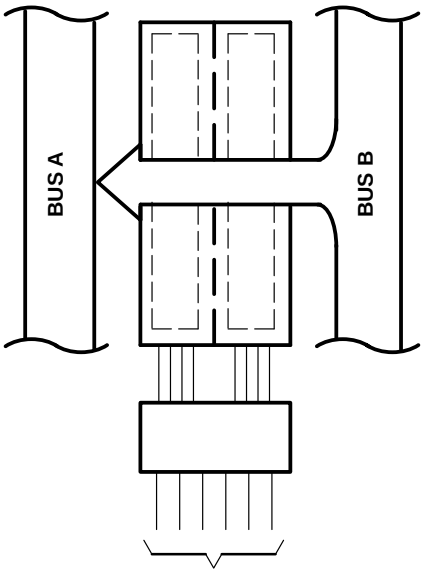
FUNCTION TABLE

INPUTS						DATA I/O		OPERATION OR FUNCTION
OEAB	$\overline{OEBA}$	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	
L	H	H or L	H or L	X	X	Input	Input	Isolation
L	H	↑	↑	X	X	Input	Input	Store A and B data
X	H	↑	H or L	X	X	Input	Unspecified†	Store A, hold B
H	H	↑	↑	X‡	X	Input	Output	Store A in both registers
L	X	H or L	↑	X	X	Unspecified†	Input	Hold A, store B
L	L	↑	↑	X	X‡	Output	input	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-time $\overline{B}$ data to A bus
L	L	X	H or L	X	H	Output	Output	Stored $\overline{B}$ data to A bus
H	H	X	X	L	X	Input	Output	Real-time $\overline{A}$ data to B bus
H	H	H or L	X	H	X	Input	Output	Stored $\overline{A}$ data to B bus
H	L	H or L	H or L	H	H	Output	Output	Stored $\overline{A}$ data to B bus and stored B data to A bus

† The data output functions may be enabled or disabled by various signals at the OEAB or $\overline{OEBA}$ inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every low-to-high transition on the clock inputs.

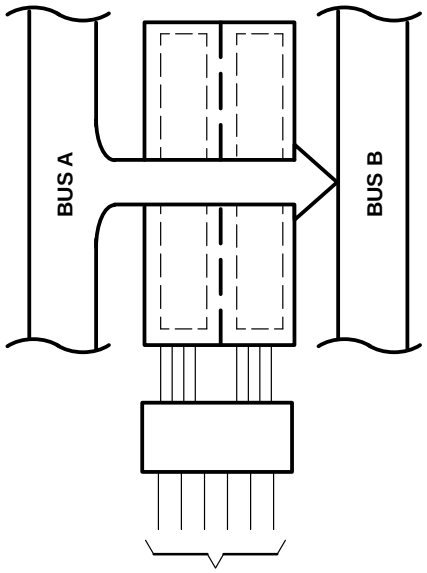
‡ When select control is low, clocks can occur simultaneously so long as allowances are made for propagation delays from A to B (B to A) plus setup and hold times. When select control is high, clocks must be staggered in order to load both registers.

PRODUCT PREVIEW



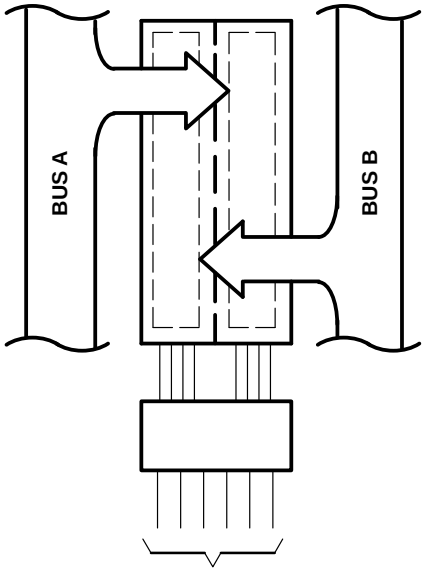
OEAB	$\overline{\text{OEBA}}$	CLKAB	CLKBA	SAB	SBA
L	L	X	X	X	L

REAL-TIME TRANSFER
BUS B TO BUS A



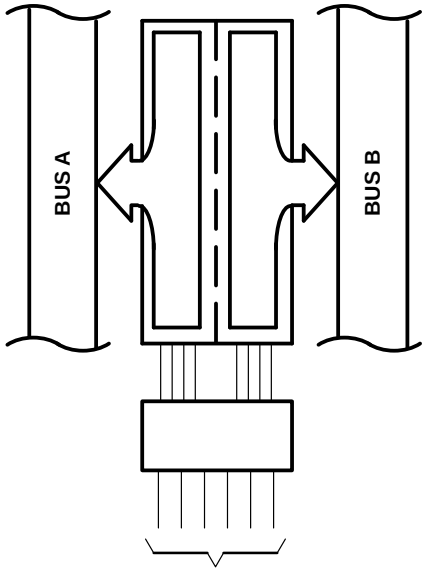
OEAB	$\overline{\text{OEBA}}$	CLKAB	CLKBA	SAB	SBA
H	H	X	X	L	X

REAL-TIME TRANSFER
BUS A TO BUS B



OEAB	$\overline{\text{OEBA}}$	CLKAB	CLKBA	SAB	SBA
X	H	↑	X	X	X
L	X	X	↑	X	X
L	H	↑	↑	X	X

STORAGE FROM
A, B, OR A AND B



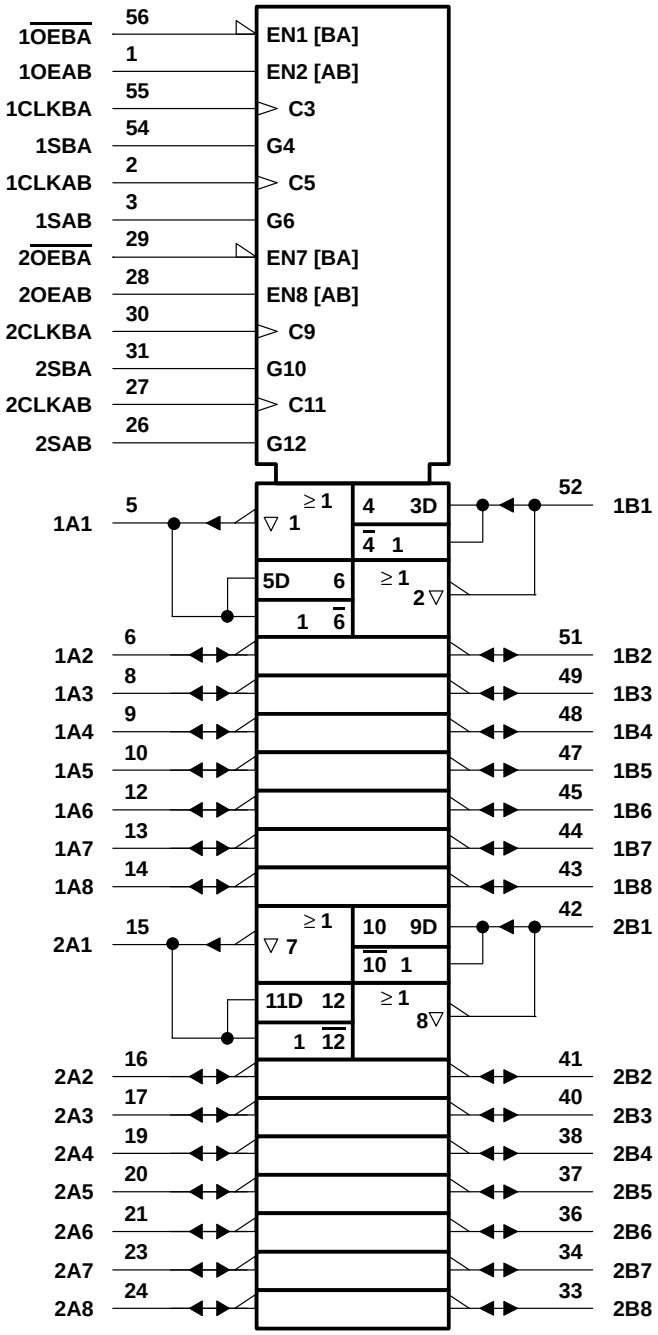
OEAB	$\overline{\text{OEBA}}$	CLKAB	CLKBA	SAB	SBA
H	L	H or L	H or L	H	H

TRANSFER STORED DATA
TO A AND/OR B

Figure 1. Bus-Management Functions

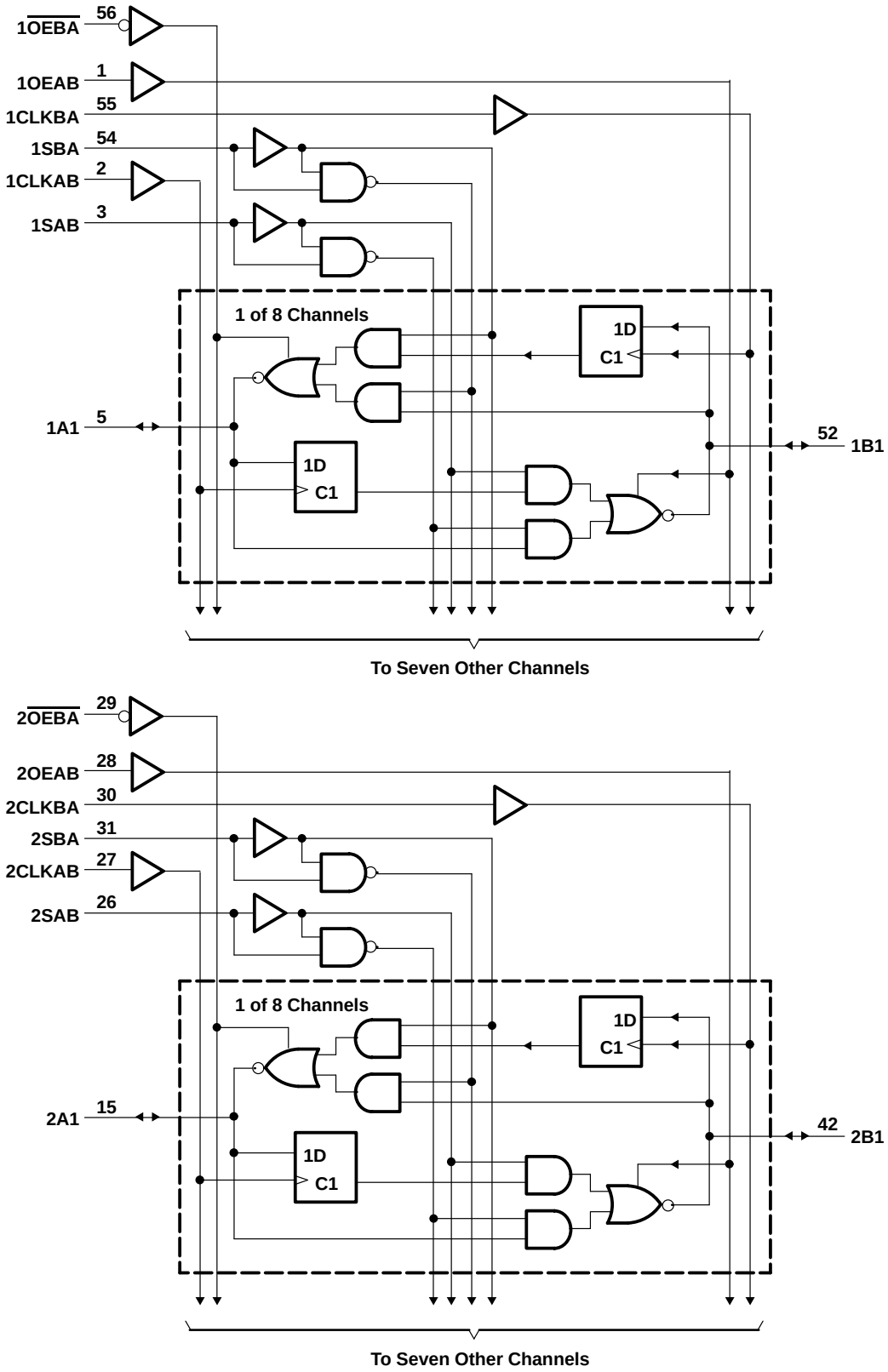
PRODUCT PREVIEW

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



PRODUCT PREVIEW

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) . . . . . –0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O . . . . . –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16651 . . . . . 96 mA
SN74ABT16651 . . . . . 128 mA
Input clamp current, I_{IK} (V_I < 0) . . . . . –18 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . –50 mA
Maximum power dissipation at T_A = 55°C (in still air) . . . . . 1 W
Storage temperature range . . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

			SN54ABT16651		SN74ABT16651		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

PRODUCT PREVIEW

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT16651		SN74ABT16651		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA				–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = – 3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = – 3 mA		3			3		3		
	V_{CC} = 4.5 V,	I_{OH} = – 24 mA		2			2				
	V_{CC} = 4.5 V,	I_{OH} = – 32 mA		2‡					2		
V_{OL}	V_{CC} = 4.5 V,	I_{OL} = 48 mA				0.55		0.55			V
	V_{CC} = 4.5 V,	I_{OL} = 64 mA				0.55‡				0.55	
I_I	V_{CC} = 5.5 V, V_I = V_{CC} or GND		Control inputs			±1		±1		±1	µA
			A or B ports			±100		±100		±100	
I_{OZH}§	V_{CC} = 5.5 V,	V_O = 2.7 V				50		50		50	µA
I_{OZL}§	V_{CC} = 5.5 V,	V_O = 0.5 V				–50		–50		–50	µA
I_{off}	V_{CC} = 0,	V_I or V_O ≤ 4.5 V				±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶	V_{CC} = 5.5 V,	V_O = 2.5 V		–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	A or B ports	Outputs high			2		2		2	mA
			Outputs low			72		72		30	
			Outputs disabled			2		2		2	
ΔI_{CC}#	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Data inputs	Outputs enabled			1		1.5		1	mA
			Outputs disabled			0.05		0.05		0.05	
		Control inputs				1.5		1.5		1.5	
C_i	V_I = 2.5 V or 0.5 V		Control inputs								pF
C_{io}	V_O = 2.5 V or 0.5 V		A or B ports								pF

† All typical values are at V_{CC} = 5 V.
‡ On products compliant to MIL-STD-883, Class B, this parameter does not apply.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

PRODUCT PREVIEW

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